

High Density Low-Profile-I.C. Socket

102HD Series

SPECIFICATIONS:

- . Current rating: 1A min.
- . Contact resistance: 20mΩ max.
- . Dielectric withstanding voltage: 800V AC/minute
- . Insulation resistance: 5000MΩ min. 500V DC
- . Temperature range: -55°C ~ +85°C
- . Insertion Force: 454 g
- . Withdrawal Force: 14.17 g
- . Contact retention force: 450 g

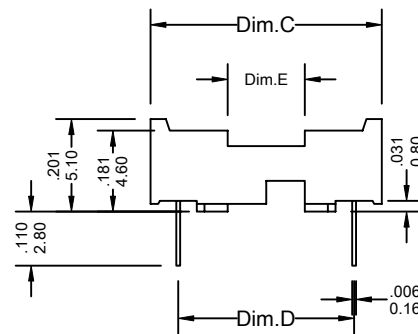
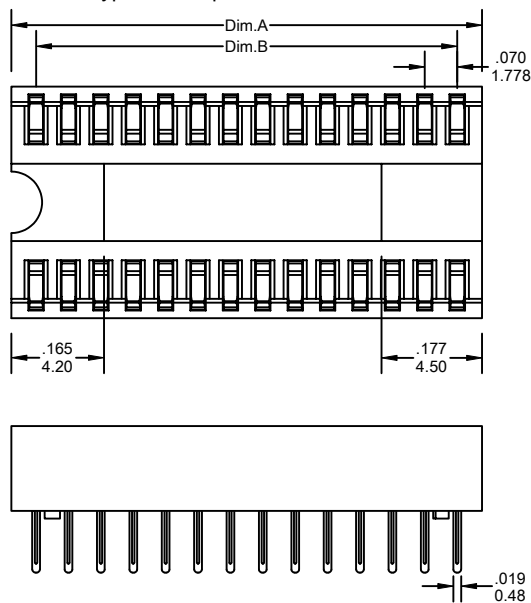
MATERIAL:

- . Insulator: Glass-filled PBT [UL94V-0]
- . Contact: Copper Alloy, tin alloy plating over copper plating

FEATURES:

- . Double beam stamped and formed contact
- . Up to 50% saving on PCB real estate
- . Closed bottom design to prevent solder wicking
- . Low profile design
- . Provided new type for flux protection

UNIT: INCH
MM

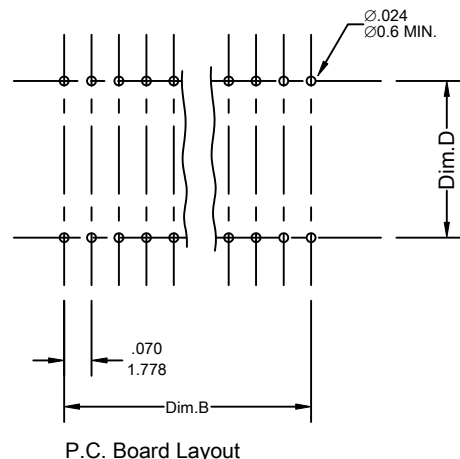


Ordering Information 102HD Series

Series No.	No. of Contacts	Contact Plating	
102HD	28P	T	PB
102HD Series	24P 40P 28P 42P 30P 64P	T: Tin	RoHs

Dimensional Information

Circuits	24	28	30	40	42	64	
Dim.A±	.008 0.20	.840 21.33	.991 25.17	1.050 26.67	1.411 35.84	1.470 37.34	2.248 57.10
Dim.B±	.008 0.20	.770 19.56	.910 23.12	.980 24.89	1.330 33.78	1.400 35.56	2.170 55.12
Dim.C±	.008 0.20	.498 12.65	.498 12.65	.498 12.65	.698 17.73	.698 17.73	.848 21.54
Dim.D±	.004 0.10	.400 10.16	.400 10.16	.400 10.16	.600 15.24	.600 15.24	.750 19.05
Dim.E±	.008 0.20	.166 4.22	.166 4.22	.166 4.22	.366 9.30	.366 9.30	.518 13.15



P.C. Board Layout